

## 2. Absolute Maximum Ratings\*

Operating Temperature (Industrial) ..	-40° C to + 85° C
Storage Temperature.....	-60° C to + 150° C
Voltage on Any Input Pin with Respect to Ground	
.....	-0.3V to max of $V_{DDIO}$
.....	+ 0.3V and 3.6V
Maximum Operating Voltage ( $V_{DDIO}$ ) .....	3.6V
Maximum Operating Voltage ( $V_{DDCORE}$ ) .....	1.95V

\*NOTICE: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### 3. DC Characteristics

The following characteristics are applicable to the Operating Temperature range:  $T_A = -40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ , unless otherwise specified and are certified for a Junction Temperature up to  $100^{\circ}\text{C}$ .

**Table 3-1.** DC Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{DDIO}$	DC Supply I/Os		2.7		3.6	V
$V_{DDCORE}$	DC Supply Core		1.65		1.95	V
$V_{IL}$	Input Low Voltage		-0.3		0.8	V
$V_{IH}$	Input High Voltage		2.0		$V_{DDIO} + 0.3$	V
$V_{OL}$	Output Low Voltage	Pin Group 1 <sup>(2)</sup> : $I_{OL} = 16\text{ mA}$ <sup>(1)</sup>			0.4	V
		Pin Group 2 <sup>(3)</sup> : $I_{OL} = 8\text{ mA}$ <sup>(1)</sup>			0.4	V
		Pin Group 3 <sup>(4)</sup> : $I_{OL} = 2\text{ mA}$ <sup>(1)</sup>			0.4	V
		All Output Pins: $I_{OL} = 0\text{ mA}$ <sup>(1)</sup>			0.2	V
$V_{OH}$	Output High Voltage	Pin Group 1 <sup>(2)</sup> : $I_{OH} = 16\text{ mA}$ <sup>(1)</sup>	$V_{DDIO} - 0.4$			V
		Pin Group 2 <sup>(3)</sup> : $I_{OH} = 8\text{ mA}$ <sup>(1)</sup>	$V_{DDIO} - 0.4$			
		Pin Group 3 <sup>(4)</sup> : $I_{OH} = 2\text{ mA}$ <sup>(1)</sup>	$V_{DDIO} - 0.4$			
		All Output Pins: $I_{OH} = 0\text{ mA}$ <sup>(1)</sup>	$V_{DDIO} - 0.2$			
$I_{LEAK}$	Input Leakage Current				10	$\mu\text{A}$
$I_{PULL}$	Input Pull-up Current	$V_{DDIO} = 3.6\text{V}$ , $V_{IN} = 0\text{V}$			280	$\mu\text{A}$
$I_{OUT}$	Output Current	Pin Group 1 <sup>(2)</sup>			16	mA
		Pin Group 2 <sup>(3)</sup> :			8	mA
		Pin Group 3 <sup>(4)</sup> :			2	mA
$C_{IN}$	Input Capacitance	TQFP100 Package			5.3	pF
$I_{SC}$	Static Current	$V_{DDIO} = 3.6\text{V}$ , $V_{DDCORE} = 1.95\text{V}$ , $MCKI = 0\text{Hz}$ All Inputs Driven $TMS, TCK, TDI, NRST = 1$	$T_A = 25^{\circ}\text{C}$		120	$\mu\text{A}$
			$T_A = 85^{\circ}\text{C}$		2.3	mA

- Notes:
1.  $I_{OL}$  = Output Current at low level.  $I_{OH}$  = Output Current at high level.
  2. Pin Group 1 = NUB/NWR1, NWE/NWR0, NOE/NRD1
  3. Pin Group 2 = D0-D15, A0/NLB, A1-A19, P28/A20/CS7, P29/A21/CS6, P30/A22/CS5, P31/A23/CS4, NCS0, NCS1, P26/NCS2, P27/NCS3
  4. Pin Group 3 = All Others

## 4. Power Consumption

The values in the following tables are values measured in the typical operating conditions (i.e.,  $V_{DDIO} = 3.3V$ ,  $V_{DDCORE} = 1.8V$ ,  $T_A = 25^\circ C$ ) on the AT91EB40A Evaluation Board and are given as demonstrative values.

**Table 4-1.** Power Consumption

Mode	Conditions	Consumption	Unit
Reset		0.02	mW/MHz
Normal	Fetch in ARM mode from internal SRAM All peripheral clocks activated	0.83	
	Fetch in ARM mode from internal SRAM All peripheral clocks deactivated	0.73	
	Fetch in ARM mode from external SRAM <sup>(1)</sup> All peripheral clocks deactivated	0.20	
	Fetch in Thumb mode from external SRAM <sup>(1)</sup> All peripheral clocks deactivated	0.24	
Idle	All peripheral clocks activated	0.16	
	All peripheral clocks deactivated	0.06	

Note: 1. With two Wait States.

**Table 4-2.** Power Consumption per Peripheral

Peripheral	Consumption	Unit
PIO Controller	15.3	$\mu W/MHz$
Timer/Counter Channel	15.0	
Timer/Counter Block (3 Channels)	36.3	
USART	27.8	

### 4.1 Thermal and Reliability Considerations

#### 4.1.1 Thermal Data

In [Table 4-3](#), the device lifetime is estimated with the MIL-217 standard in the “moderately controlled” environmental model (this model is described as corresponding to an installation in a permanent rack with adequate cooling air), depending on the device Junction Temperature. (For details see the section [“Junction Temperature” on page 5.](#))

Note that the user must be extremely cautious with this MTBF calculation: as the MIL-217 model is pessimistic with respect to observed values due to the way the data/models are obtained (test under severe conditions). The life test results that have been measured are always better than the predicted ones.

**Table 4-3.** MTBF Versus Junction Temperature

Junction Temperature ( $T_J$ ) (°C)	Estimated Lifetime (MTBF) (Year)
100	10
125	5
150	3
175	2

Table 4-4 summarizes the thermal resistance data related to the package of interest.

**Table 4-4.** Thermal Resistance Data

Symbol	Parameter	Condition	Package	Typ	Unit
$\theta_{JA}$	Junction-to-ambient thermal resistance	Still Air	TQFP100	40	°C/W
$\theta_{JC}$	Junction-to-case thermal resistance		TQFP100	6.4	

#### 4.1.2 Reliability Data

The number of gates and the device die size are provided for the user to calculate reliability data with another standard and/or in another environmental model.

**Table 4-5.** Reliability Data

Parameter	Data	Unit
Number of Logic Gates	280	K gates
Number of Memory Gates	12,897	K gates
Device Die Size	21.2	mm <sup>2</sup>

## 4.2 Junction Temperature

The average chip-junction temperature  $T_J$  in °C can be obtained from the following:

- $T_J = T_A + (P_D \times \theta_{JA})$
- $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

Where:

- $\theta_{JA}$  = package thermal resistance, Junction-to-ambient (°C/W), provided in [Table 4-4 on page 5](#).
- $\theta_{JC}$  = package thermal resistance, Junction-to-case thermal resistance (°C/W), provided in [Table 4-4 on page 5](#).
- $\theta_{HEAT\ SINK}$  = cooling device thermal resistance (°C/W), provided in the device datasheet.
- $P_D$  = device power consumption (W) estimated from data provided in the section "[Power Consumption](#)" on [page 4](#).
- $T_A$  = ambient temperature (°C).

From the first equation, the user can derive the estimated lifetime of the chip and thereby decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature  $T_J$  in °C

## 5. Conditions

### 5.1 Timing Results

The delays are given as typical values in the following conditions:

- $V_{DDIO} = 3.0V$
- $V_{DDCORE} = 1.8V$
- Ambient Temperature = 25° C
- Load Capacitance = 0 pF
- The output level change detection is  $0.5 \times V_{DDIO}$
- The input level is  $0.8V$  for a low-level detection and is  $2.0V$  for a high level detection.

The minimum and maximum values given in the AC characteristic tables of this datasheet take into account the process variation and the design.

In order to obtain the timing for other conditions, the following equation should be used:

$$t = \delta_{T^{\circ}} \times \left( (\delta_{VDDCORE} \times t_{DATASHEET}) + \left( \delta_{VDDIO} \times \sum C_{SIGNAL} \times \delta_{CSIGNAL} \right) \right)$$

Where:

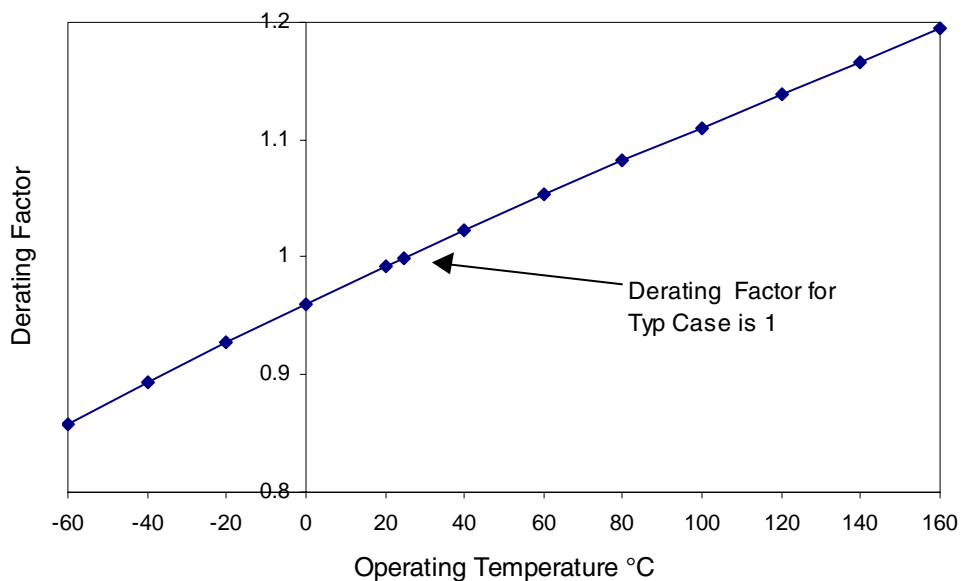
- $\delta_{T^{\circ}}$  is the derating factor in temperature given in [Figure 5-1](#).
- $\delta_{VDDCORE}$  is the derating factor for the Core Power Supply given in [Figure 5-2 on page 7](#).
- $t_{DATASHEET}$  is the minimum or maximum timing value given in this datasheet for a load capacitance of 0 pF.
- $\delta_{VDDIO}$  is the derating factor for the I/O Power Supply given in [Figure 5-3 on page 8](#).
- $C_{SIGNAL}$  is the capacitance load on the considered output pin.<sup>(1)</sup>
- $\delta_{CSIGNAL}$  is the load derating factor depending on the capacitance load on the related output pins given in Min and Max values in this datasheet.

The input delays are given as typical values.

Note: The user must take into account the package capacitance load contribution ( $C_{IN}$ ) described in [Table 3-1 on page 3](#).

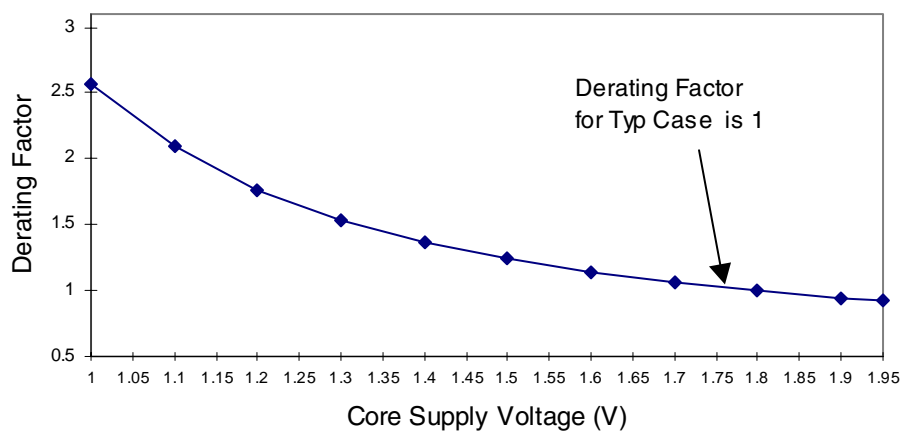
## 5.2 Temperature Derating Factor

Figure 5-1. Derating Curve for Different Operating Temperatures



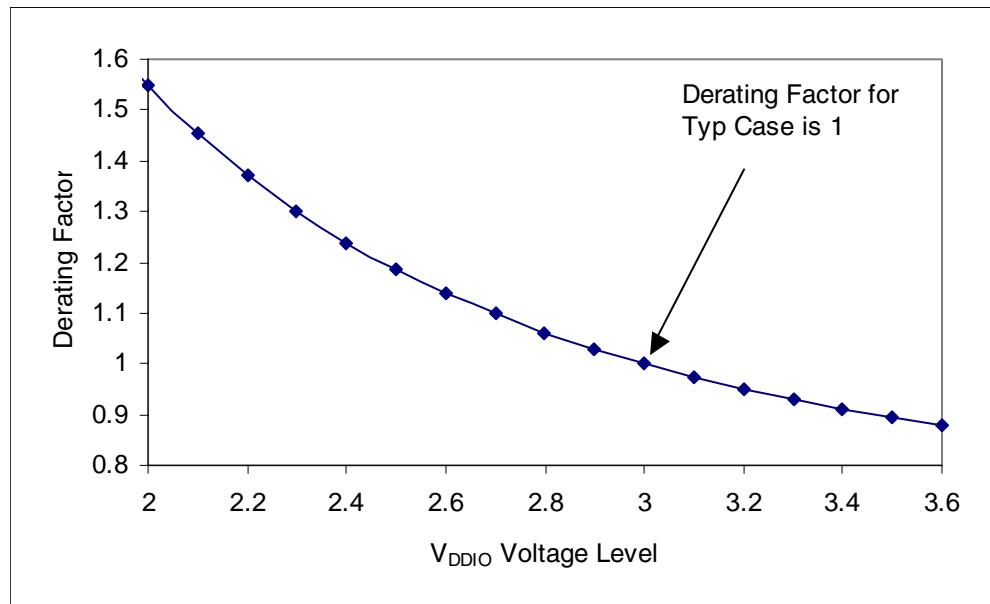
## 5.3 Core Voltage Derating Factor

Figure 5-2. Core Voltage Derating Factor



## 5.4 IO Voltage Derating Factor

**Figure 5-3.** Derating Factor for Different  $V_{DDIO}$  Power Supply Levels



## 6. Clock Waveforms

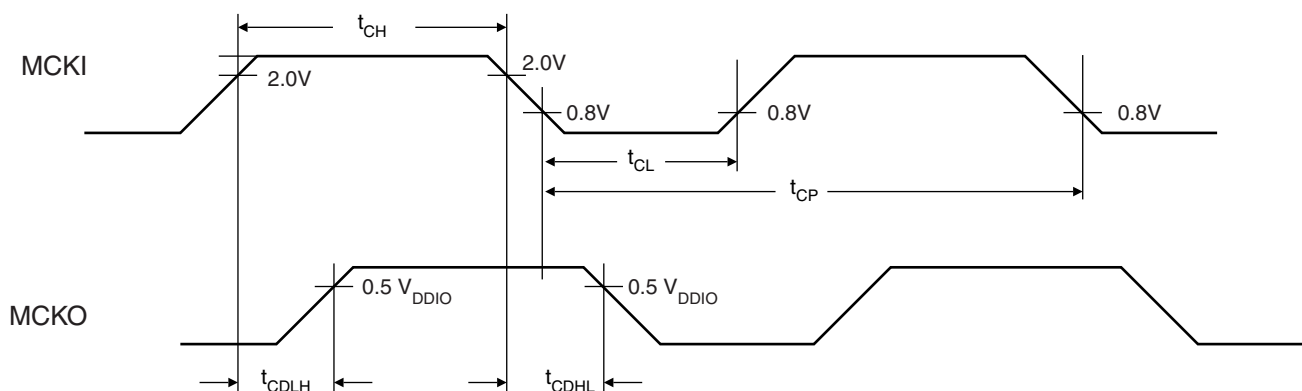
**Table 6-1.** Master Clock Waveform Parameters

Symbol	Parameter	Conditions	Min	Max	Units
$1/(t_{CP})$	Oscillator Frequency			82.1	MHz
$t_{CP}$	Oscillator Period		12.2		ns
$t_{CH}$	High Half-period		5.0		ns
$t_{CL}$	Low Half-period		5.5		ns

**Table 1.** Clock Propagation Times

Symbol	Parameter	Conditions	Min	Max	Units
$t_{CDLH}$	Rising Edge Propagation Time	$C_{MCKO} = 0 \text{ pF}$	4.4	6.6	ns
		$C_{MCKO}$ derating	0.199	0.295	ns/pF
$t_{CDHL}$	Falling Edge Propagation Time	$C_{MCKO} = 0 \text{ pF}$	4.5	6.7	ns
		$C_{MCKO}$ derating	0.153	0.228	ns/pF

**Figure 6-1.** Clock Waveform

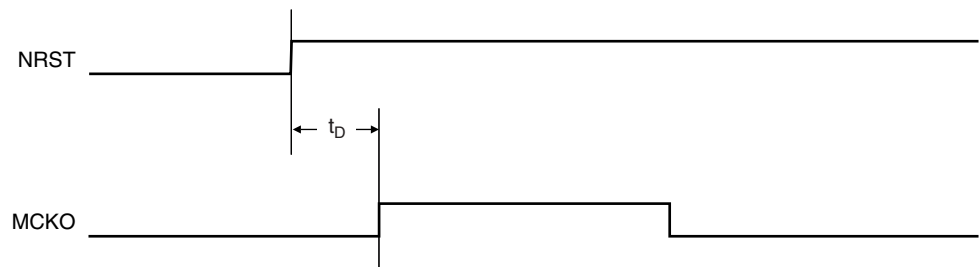


**Table 6-2.** NRST to MCKO

Symbol	Parameter	Min	Max	Units
$t_D$	NRST Rising Edge to MCKO Valid Time	$3(t_{CP}/2)$	$7(t_{CP}/2)$	ns



**Figure 6-2.** MCKO Relative to NRST



## 7. AC Characteristics

### 7.1 EBI Signals Relative to MCKI

The following tables show timings relative to operating condition limits defined in the section "Timing Results" on page 6. See Figure 7-1 on page 14.

**Table 7-1.** General-purpose EBI Signals

Symbol	Parameter	Conditions	Min	Max	Units
EBI <sub>1</sub>	MCKI Falling to NUB Valid	C <sub>NUB</sub> = 0 pF	4.4	8.9	ns
		C <sub>NUB</sub> derating	0.030	0.043	ns/pF
EBI <sub>2</sub>	MCKI Falling to NLB/A0 Valid	C <sub>NLB</sub> = 0 pF	3.7	6.7	ns
		C <sub>NLB</sub> derating	0.045	0.069	ns/pF
EBI <sub>3</sub>	MCKI Falling to A1 - A23 Valid	C <sub>ADD</sub> = 0 pF	3.4	7.8	ns
		C <sub>ADD</sub> derating	0.045	0.076	ns/pF
EBI <sub>4</sub>	MCKI Falling to Chip Select Change	C <sub>NCS</sub> = 0 pF	3.7	8.6	ns
		C <sub>NCS</sub> derating	0.045	0.078	ns/pF
EBI <sub>5</sub>	NWAIT Setup before MCKI Rising		1.7		ns
EBI <sub>6</sub>	NWAIT Hold after MCKI Rising		1.7		ns

**Table 7-2.** EBI Write Signals

Symbol	Parameter	Conditions	Min	Max	Units
EBI <sub>7</sub>	MCKI Rising to NWR Active (No Wait States)	C <sub>NWR</sub> = 0 pF	3.9	6.3	ns
		C <sub>NWR</sub> derating	0.029	0.043	ns/pF
EBI <sub>8</sub>	MCKI Rising to NWR Active (Wait States)	C <sub>NWR</sub> = 0 pF	4.4	7.0	ns
		C <sub>NWR</sub> derating	0.029	0.043	ns/pF
EBI <sub>9</sub>	MCKI Falling to NWR Inactive (No Wait States)	C <sub>NWR</sub> = 0 pF	3.8	6.3	ns
		C <sub>NWR</sub> derating	0.029	0.044	ns/pF
EBI <sub>10</sub>	MCKI Rising to NWR Inactive (Wait States)	C <sub>NWR</sub> = 0 pF	4.2	6.7	ns
		C <sub>NWR</sub> derating	0.029	0.044	ns/pF
EBI <sub>11</sub>	MCKI Rising to D0 - D15 Out Valid	C <sub>DATA</sub> = 0 pF	4.2	7.5	ns
		C <sub>DATA</sub> derating	0.045	0.080	ns/pF
EBI <sub>12</sub>	NWR High to NUB Change	C <sub>NUB</sub> = 0 pF	3.1	7.0	ns
		C <sub>NUB</sub> derating	0.030	0.043	ns/pF
EBI <sub>13</sub>	NWR High to NLB/A0 Change	C <sub>NLB</sub> = 0 pF	3.1	5.4	ns
		C <sub>NLB</sub> derating	0.043	0.073	ns/pF
EBI <sub>14</sub>	NWR High to A1 - A23 Change	C <sub>ADD</sub> = 0 pF	2.9	7.0	ns
		C <sub>ADD</sub> derating	0.043	0.076	ns/pF

**Table 7-2. EBI Write Signals (Continued)**

Symbol	Parameter	Conditions	Min	Max	Units
EBI <sub>15</sub>	NWR High to Chip Select Inactive	C <sub>NCS</sub> = 0 pF	2.9	6.8	ns
		C <sub>NCS</sub> derating	0.052	0.067	ns/pF
EBI <sub>16</sub>	Data Out Valid before NWR High (No Wait States) <sup>(1)</sup>	C = 0 pF	t <sub>CH</sub> - 1.8		ns
		C <sub>DATA</sub> derating	-0.080		ns/pF
		C <sub>NWR</sub> derating	0.044		ns/pF
EBI <sub>17</sub>	Data Out Valid before NWR High (Wait States) <sup>(1)</sup>	C = 0 pF	n x t <sub>CP</sub> - 1.3 <sup>(2)</sup>		ns
		C <sub>DATA</sub> derating	-0.080		ns/pF
		C <sub>NWR</sub> derating	0.044		ns/pF
EBI <sub>18</sub>	Data Out Valid after NWR High		2.2		ns
EBI <sub>19</sub>	NWR Minimum Pulse Width (No Wait States) <sup>(1)</sup>	C <sub>NWR</sub> = 0 pF	t <sub>CH</sub> - 0.6		ns
		C <sub>NWR</sub> derating	0		ns/pF
EBI <sub>20</sub>	NWR Minimum Pulse Width (Wait States) <sup>(1)</sup>	C <sub>NWR</sub> = 0 pF	n x t <sub>CP</sub> - 0.9 <sup>(2)</sup>		ns
		C <sub>NWR</sub> derating	0		ns/pF

Notes: 1. The derating factor should not be applied to t<sub>CH</sub> or t<sub>CP</sub>  
2. n = number of standard wait states inserted.

**Table 7-3. EBI Read Signals**

Symbol	Parameter	Conditions	Min	Max	Units
EBI <sub>21</sub>	MCKI Falling to NRD Active <sup>(1)</sup>	C <sub>NRD</sub> = 0 pF	4.5	7.9	ns
		C <sub>NRD</sub> derating	0.029	0.043	ns/pF
EBI <sub>22</sub>	MCKI Rising to NRD Active <sup>(2)</sup>	C <sub>NRD</sub> = 0 pF	3.8	7.3	ns
		C <sub>NRD</sub> derating	0.029	0.043	ns/pF
EBI <sub>23</sub>	MCKI Falling to NRD Inactive <sup>(1)</sup>	C <sub>NRD</sub> = 0 pF	4.1	6.5	ns
		C <sub>NRD</sub> derating	0.030	0.044	ns/pF
EBI <sub>24</sub>	MCKI Falling to NRD Inactive <sup>(2)</sup>	C <sub>NRD</sub> = 0 pF	3.9	5.8	ns
		C <sub>NRD</sub> derating	0.030	0.044	ns/pF
EBI <sub>25</sub>	D0 - D15 In Setup before MCKI Falling Edge <sup>(5)</sup>		1.5		ns
EBI <sub>26</sub>	D0 - D15 In Hold after MCKI Falling Edge <sup>(6)</sup>		1.2		ns
EBI <sub>27</sub>	NRD High to NUB Change	C <sub>NUB</sub> = 0 pF	3.2	7.1	ns
		C <sub>NUB</sub> derating	0.030	0.043	ns/pF
EBI <sub>28</sub>	NRD High to NLB/A0 Change	C <sub>NLB</sub> = 0 pF	3.2	4.6	ns
		C <sub>NLB</sub> derating	0.043	0.073	ns/pF
EBI <sub>29</sub>	NRD High to A1 - A23 Change	C <sub>ADD</sub> = 0 pF	2.8	6.1	ns
		C <sub>ADD</sub> derating	0.043	0.076	ns/pF
EBI <sub>30</sub>	NRD High to Chip Select Inactive	C <sub>NCS</sub> = 0 pF	2.9	6.2	ns
		C <sub>NCS</sub> derating	0.052	0.067	ns/pF

**Table 7-3.** EBI Read Signals

Symbol	Parameter	Conditions	Min	Max	Units
EBI <sub>31</sub>	Data Setup before NRD High <sup>(6)</sup>	C <sub>NRD</sub> = 0 pF	8.0		ns
		C <sub>NRD</sub> derating	0.044		ns/pF
EBI <sub>32</sub>	Data Hold after NRD High <sup>(6)</sup>	C <sub>NRD</sub> = 0 pF	-3.1		ns
		C <sub>NRD</sub> derating	-0.030		ns/pF
EBI <sub>33</sub>	NRD Minimum Pulse Width <sup>(1) (3)</sup>	C <sub>NRD</sub> = 0 pF	(n + 1) t <sub>CP</sub> - 1.9 <sup>(4)</sup>		ns
		C <sub>NRD</sub> derating	0.001		ns/pF
EBI <sub>34</sub>	NRD Minimum Pulse Width <sup>(2) (3)</sup>	C <sub>NRD</sub> = 0 pF	n x t <sub>CP</sub> + (t <sub>CH</sub> - 1.5) <sup>(4)</sup>		ns
		C <sub>NRD</sub> derating	0.001		ns/pF

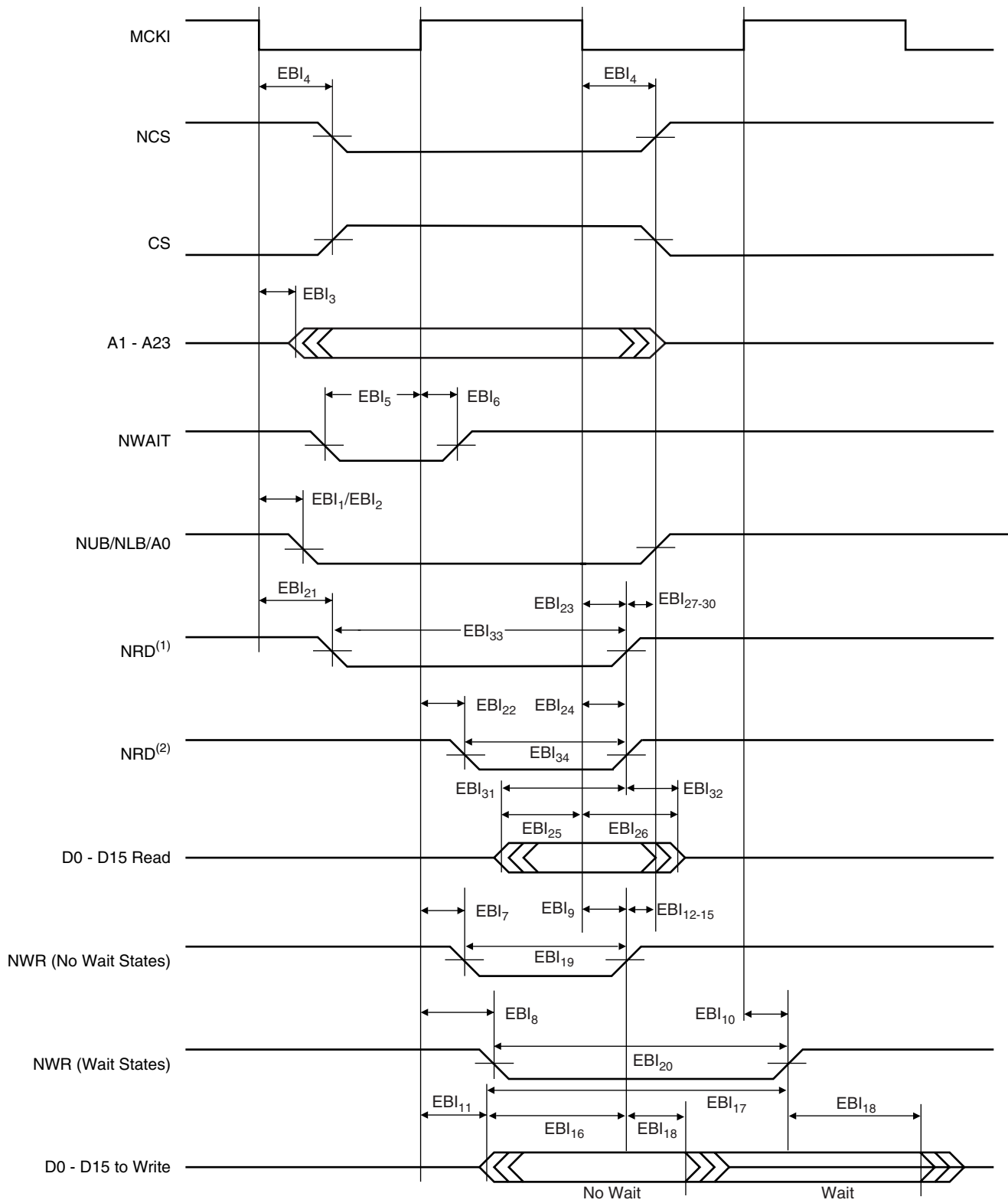
- Notes:
1. Early Read Protocol.
  2. Standard Read Protocol.
  3. The derating factor should not be applied to t<sub>CH</sub> or t<sub>CP</sub>
  4. n = number of standard wait states inserted.
  5. Only one of these two timings, EB<sub>25</sub> or EBI<sub>31</sub>, needs to be met.
  6. Only one of these two timings, EB<sub>26</sub> or EBI<sub>32</sub>, needs to be met.

**Table 7-4.** EBI Read and Write Control Signals. Capacitance Limitation

Symbol	Parameter	Conditions	Min	Max	Units
T <sub>CPLNRD</sub> <sup>(1)</sup>	Master Clock Low Due to NRD Capacitance	C <sub>NRD</sub> = 0 pF	7.3		ns
		C <sub>NRD</sub> derating	0.044		ns/pF
T <sub>CPLNWR</sub> <sup>(2)</sup>	Master CLock Low Due to NWR Capacitance	C <sub>NWR</sub> = 0 pF	7.6		ns
		C <sub>NWR</sub> derating	0.044		ns/pF

- Notes:
1. If this condition is not met, the action depends on the read protocol intended for use.
    - Early Read Protocol: Programing an additional t<sub>DF</sub> (Data Float Output Time) cycle.
    - Standard Read Protocol: Programming an additional t<sub>DF</sub> Cycle and an additional wait state.
  2. Applicable only for chip select programmed with 0 wait state. If this condition is not met, at least one wait state must be programmed.

**Figure 7-1.** EBI Signals Relative to MCKI



Notes: 1. Early Read Protocol.  
2. Standard Read Protocol.

## 7.2 Peripheral Signals

### 7.2.1 USART Signals

The inputs have to meet the minimum pulse width and period constraints shown in [Table 7-5](#) and [Table 7-6](#), and represented in [Figure 7-2](#).

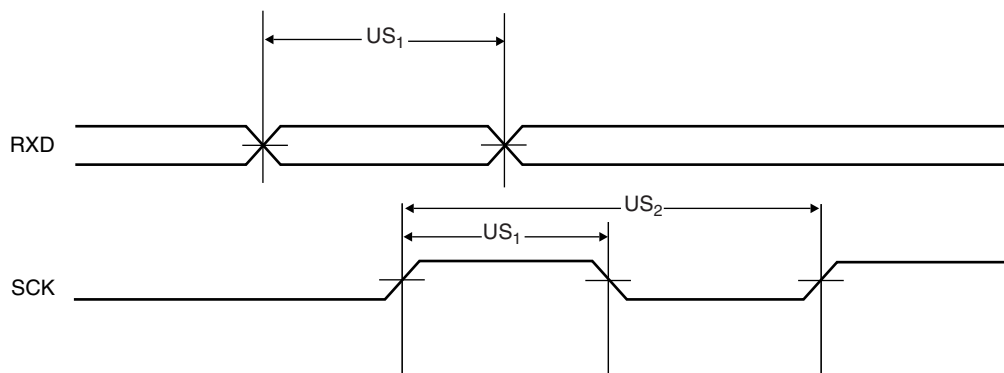
**Table 7-5.** USART Input Minimum Pulse Width

Symbol	Parameter	Min Pulse Width	Units
US <sub>1</sub>	SCK/RXD Minimum Pulse Width	$5(t_{CP}/2)$	ns

**Table 7-6.** USART Minimum Input Period

Symbol	Parameter	Min Input Period	Units
US <sub>2</sub>	SCK Minimum Input Period	$9(t_{CP}/2)$	ns

**Figure 7-2.** USART Signals



### 7.2.2 Timer/Counter Signals

Due to internal synchronization of input signals, there is a delay between an input event and a corresponding output event. This delay is  $3(t_{CP})$  in Waveform Event Detection mode and  $4(t_{CP})$  in Waveform Total-count Detection mode. The inputs have to meet the minimum pulse width and minimum input period shown in [Table 7-7](#) and [Table 7-8](#), and as represented in [Figure 7-3](#).

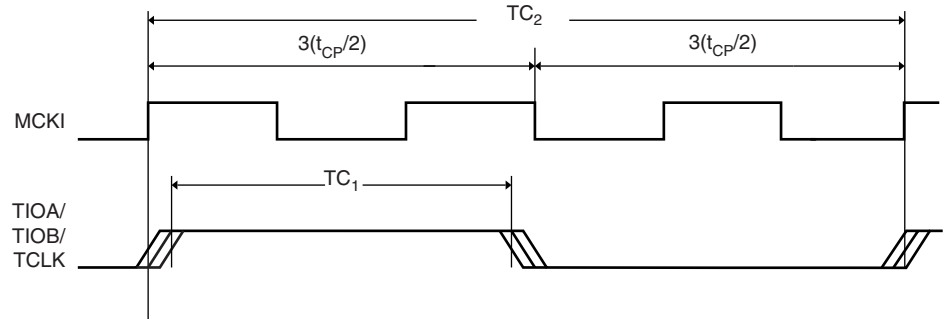
**Table 7-7.** Timer Input Minimum Pulse Width

Symbol	Parameter	Min Pulse Width	Units
TC <sub>1</sub>	TCLK/TIOA/TIOB Minimum Pulse Width	$3(t_{CP}/2)$	ns

**Table 7-8.** Timer Input Minimum Period

Symbol	Parameter	Min Input Period	Units
$TC_2$	TCLK/TIOA/TIOB Minimum Input Period	$5(t_{CP}/2)$	ns

**Figure 7-3.** Timer Input



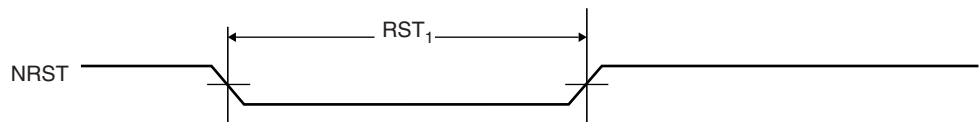
### 7.2.3 Reset Signals

A minimum pulse width is necessary, as shown in [Table 7-9](#) and as represented in [Figure 7-4](#).

**Table 7-9.** Reset Minimum Pulse Width

Symbol	Parameter	Min Pulse-width	Units
$RST_1$	NRST Minimum Pulse Width	$10(t_{CP})$	ns

**Figure 7-4.** Reset Signal



Only the NRST rising edge is synchronized with MCKI. The falling edge is asynchronous.

### 7.2.4 Advanced Interrupt Controller Signals

Inputs have to meet the minimum pulse width and minimum input period shown in [Table 7-10](#) and [Table 7-11](#) and represented in [Figure 7-5](#).

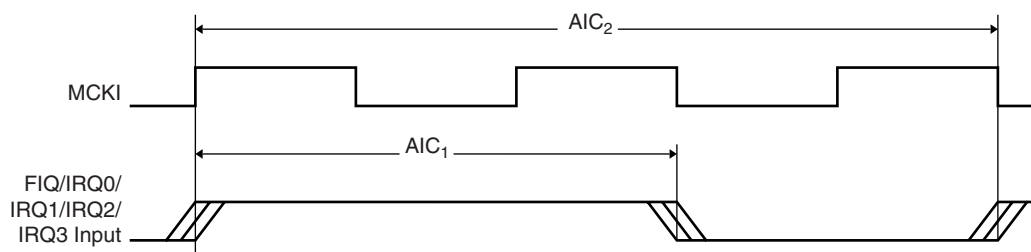
**Table 7-10.** AIC Input Minimum Pulse Width

Symbol	Parameter	Min Pulse Width	Units
AIC <sub>1</sub>	FIQ/IRQ0/IRQ1/IRQ2/IRQ3 Minimum Pulse Width	$3(t_{CP}/2)$	ns

**Table 7-11.** AIC Input Minimum Period

Symbol	Parameter	Min Input Period	Units
AIC <sub>2</sub>	AIC Minimum Input Period	$5(t_{CP}/2)$	ns

**Figure 7-5.** AIC Signals



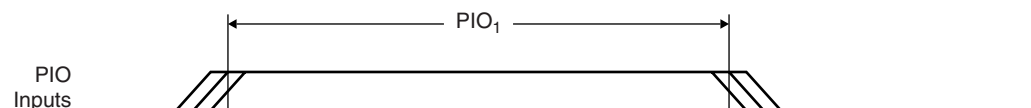
## 7.2.5 Parallel I/O Signals

The inputs have to meet the minimum pulse width shown in [Table 7-12](#) and represented in [Figure 7-6](#).

**Table 7-12.** PIO Input Minimum Pulse Width

Symbol	Parameter	Min Pulse Width	Units
PIO <sub>1</sub>	PIO Input Minimum Pulse Width	$3(t_{CP}/2)$	ns

**Figure 7-6.** PIO Signal



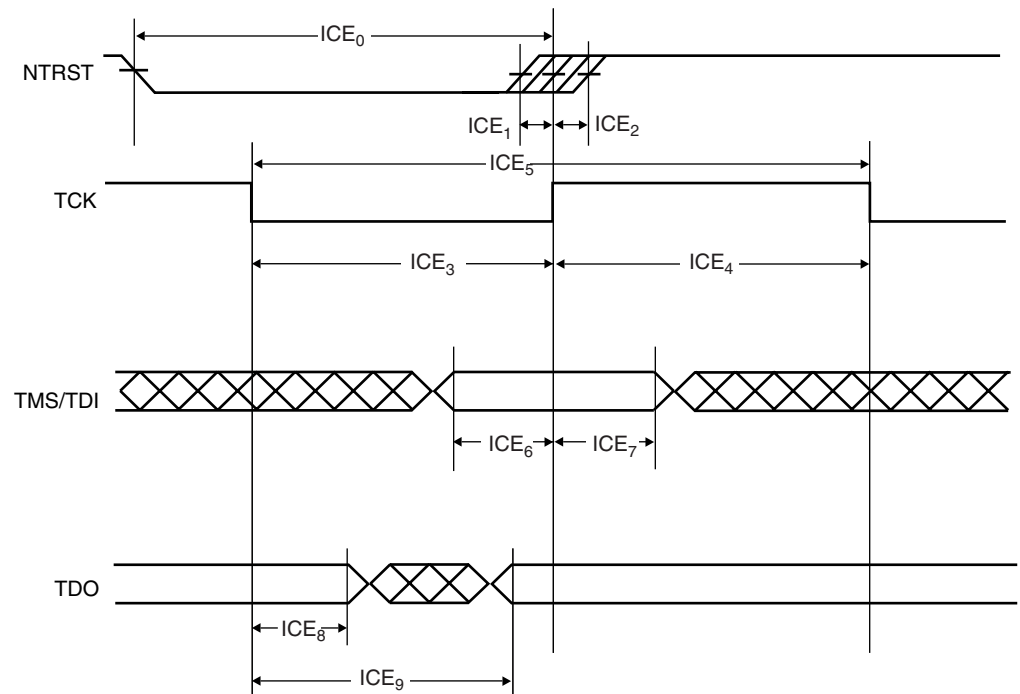


## 7.2.6 ICE Interface Signals

**Table 7-13.** ICE Interface Timing Specifications

Symbol	Parameter	Conditions	Min	Max	Units
ICE <sub>0</sub>	NTRST Minimum Pulse Width		10.9		ns
ICE <sub>1</sub>	NTRST High Recovery to TCK High		0.9		ns
ICE <sub>2</sub>	NTRST High Removal from TCK High		-0.3		ns
ICE <sub>3</sub>	TCK Low Half-period		23.5		ns
ICE <sub>4</sub>	TCK High Half-period		22.7		ns
ICE <sub>5</sub>	TCK Period		46.1		ns
ICE <sub>6</sub>	TDI, TMS Setup before TCK High		0.4		ns
ICE <sub>7</sub>	TDI, TMS Hold after TCK High		0.4		ns
ICE <sub>8</sub>	TDO Hold Time	C <sub>TDO</sub> = 0 pF	3.3		ns
		C <sub>TDO</sub> derating	0.001		ns/pF
ICE <sub>9</sub>	TCK Low to TDO Valid	C <sub>TDO</sub> = 0 pF		7.4	ns
		C <sub>TDO</sub> derating		0.28	ns/pF

**Figure 7-7.** ICE Interface Signal



## Revision History

Version	page	Comments
1795A		10-Dec-01 First Issue
1795B		7-Aug-2002
	page 2	Absolute Maximum Ratings: changed
	page 2	Table 1. DC Characteristics: changed
	page 3	Table 2. Power Consumption: changed
	page 3	Table 3. Power Consumption per Peripheral: changed
	page 9	Table 7. Master Waveclock Parameters: changed
1795C		24-Mar-2004
	page 1	Features: Change to "Fully Static Operation" values.
	page 9	Figure 4. Clock Waveform: $t_R$ and $t_F$ removed, $t_{CL}$ measurement changed.
	page 13	Table 12. Footnote 5 changed and footnote 6 added to clarify selection needs.
1795D		22-Oct-04
	page 6	Change to Timing Results (CSR 04-320)
	page 9	Change to Table 7 and Figure 4 (CSR 04-320)
1795E		12-Dec-05
	all	Reformatted in Atmel template version 5.2. Numbering properties are changed as a result.
	page 9	Table 6-1, "Master Clock Waveform Parameters," note deleted. (CSR 05-446)



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